DSC5G02

Silicon NPN epitaxial planar type

For high-frequency amplification DSC2G02 in SMini3 type package

■ Features

- High transition frequency f_T
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

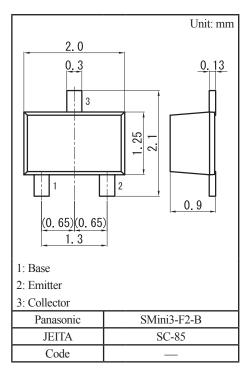
■ Marking Symbol: C5

■ Packaging

DSC5G02×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|------------------|-------------|------|
| Collector-base voltage (Emitter open) | V _{CBO} | 30 | V |
| Collector-emitter voltage (Base open) | V _{CEO} | 20 | V |
| Emitter-base voltage (Collector open) | V _{EBO} | 3 | V |
| Collector current | I_{C} | 15 | mA |
| Collector power dissipation | P _C | 150 | mW |
| Junction temperature | T _j | 150 | °C |
| Operating ambient temperature | T _{opr} | -40 to +85 | °C |
| Storage temperature | T _{stg} | -55 to +150 | °C |



■ Electrical Characteristics $T_a = 25$ °C±3°C

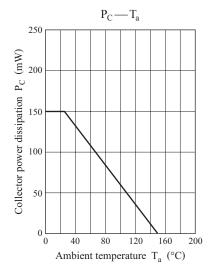
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|--------------------|--|-----|------|-----|------|
| Collector-base voltage (Emitter open) | V _{CBO} | $I_C = 10 \mu A, I_E = 0$ | 30 | | | V |
| Emitter-base voltage (Collector open) | V_{EBO} | $I_E = 10 \mu A, I_C = 0$ | 3 | | | V |
| Base-emitter voltage | V_{BE} | $V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$ | | 0.72 | | V |
| Forward current transfer ratio *1 | h _{FE} | $V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$ | 65 | | 260 | _ |
| Transition frequency | f_T | $V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}$ | 450 | 650 | | MHz |
| Reverse transfer capacitance (Common emitter) | C _{re} | $V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 10.7 \text{ MHz}$ | | 0.6 | | pF |
| Power gain | PG | $V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$ | | 24 | | dB |
| Noise figure | NF | $V_{CE} = 6 \text{ V}, I_{C} = 1 \text{ mA}, f = 100 \text{ MHz}$ | | 3.3 | | dB |

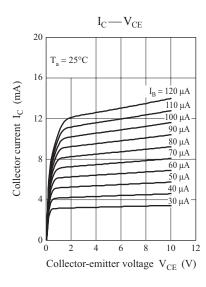
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

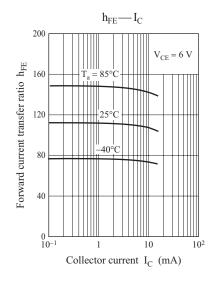
2. *1: Rank classification

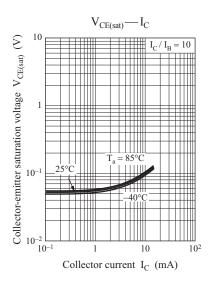
| Code | С | D | 0 | |
|-------------------|-----------|------------|-----------|--|
| Rank | С | D | No-rank | |
| h_{FE} | 65 to 160 | 100 to 260 | 65 to 260 | |
| Marking Symbol | C5C | C5D | C5 | |

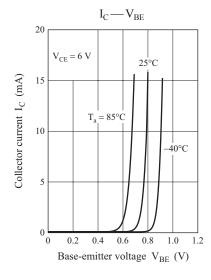
Product of no-rank is not classified and have no marking symbol for rank.

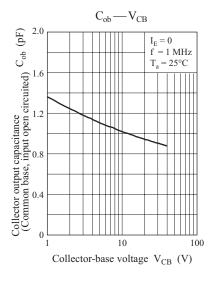


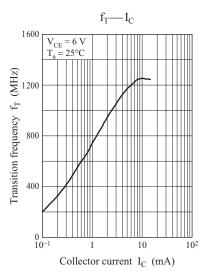








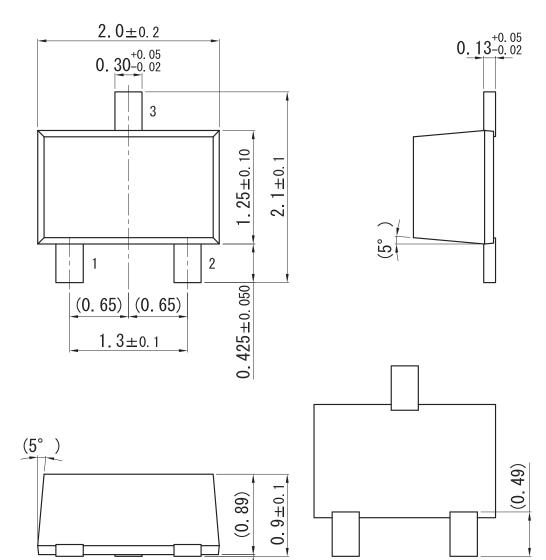




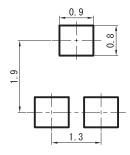
Ver. CED 2

SMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



0 to 0.1

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